

PATENT TESSERA 3.3-018

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re patent application of
Khandros et al.

: Group Art Unit 2104

Serial No. 08/030,194

: Examiner

Filed: April 28, 1993

: Date: August 24, 1993

For: SEMICONDUCTOR CHIP ASSEMBLIES,
METHODS OF MAKING SAME AND
COMPONENTS FOR SAME

X

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

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AMENDMENT AND INFORMATION DISCLOSURE STATEMENT

GROUP 2100

Sir:

Prior to examination of the above-referenced
application, please amend said application as follows.

IN THE CLAIMS

Claim 27 line 1, change "claim 27" to read--claim 23--.

Claim 34 line 1, delete "33 or";

line 3, change "or" to read --of--.

Cancel claims 39 - 55 inclusive.

Insert the following new claims:

61. A module comprising:

a substrate having a top surface, contact pads on the
top surface, external connections and conductors interconnecting
the contact pads with one another and with said external
connections in a preselected pattern of interconnection;

a plurality of semiconductor chips, each having a
plurality of surfaces and having contacts on at least one of such
surfaces;

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